

Introduction

All dimensions, operating characteristics, specifications and materials shown in this catalog are for reference only and are subject to change without notice. The data in this catalog shows nominal values; that is, they can exceed or fall short of specified values taking into account the effect of other parameters.

C&K Components assumes no liability resulting from misapplication of its products.

Agency Approvals

Many of our products are suitable for power switching, and are available with approvals by one or more of the following listing agencies:



File No. E42363 Recognized under the recognized component program of Underwriters Laboratories, Inc.

Wiring harness certified under file no. E130055

Some switches are supplied with agency approvals automatically when ordered with the appropriate contact materials (eg: E Series, 8500 Series). In some series, switches have agency approvals only when specific model numbers are selected (eg: 7000 Series, 8020 Series). Otherwise, no approvals appear on the switches. See the appropriate switch section for ratings, agency approvals and other specifications. Also see CONTACT MATERIAL.

Note:

Switches with contact material option of 'G' are electrically equivalent to 'B' and 'Q' contact materials and can be used where either dry circuit* or power conditions are encountered. When the dry circuit rating is exceeded, the gold plating is removed from the contact interface and the switch cannot then be used in dry circuits. 'G' contact material should be specified where UL approval is required on a switch used in a dry circuit application.

* Dry Circuit: Conditions where no arcing occurs during switching (i.e., 0.4 VA max. @ 20 V AC or DC max.)

ISO / QS

C&K design and manufacturing locations in Dole (France), Huizhou (China), and Waltham (Massachusetts) are certified to ISO 9001, ISO 14001, and IATF 16949. The Dole facility is also certified to EN 9100.

Contact Material

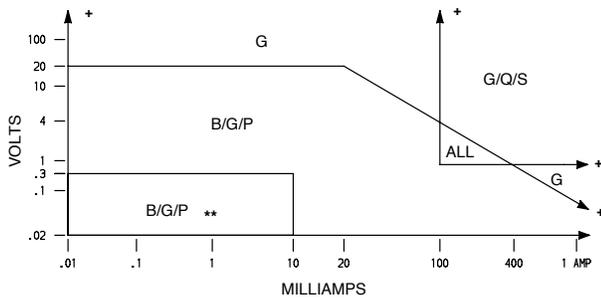
Many of our switches offer three contact material options: gold, silver, and gold over silver. Switch terminal plating may be gold, silver, tin-lead or matte tin. See desired switch section for availability of specific options. Also see Agency Approvals section included in this catalog. Figures 1 & 2 below provide contact material vs rating recommendations. For special requirements or assistance, consult Customer Service Center.

Contact Material	Characteristics
Gold (B) Gold with tin terminals (P)	Low level or dry circuit rated: 0.4 VA B/G/P DC max. Contact material: Gold
Silver (Q) Silver with tin terminals (S)	Power rated: Ratings from 100mA to 10 AMPS @ 125 V AC are available. See switch sections for applicable ratings and available agency approvals. Contact material: Silver
Gold (G)	Power or low level/dry circuit rated: Electrically equivalent to 'B, Q, contact materials and can be used where either low level/dry circuit* or power conditions are encountered. When the dry circuit rating is exceeded, the gold plating is removed from the contact interface and the switch cannot then be used in dry circuits. 'G' contact material should be specified where agency approvals are required on a switch used in a dry circuit application. Contact material: Gold over silver

Note:

* Dry Circuit: Conditions where no arcing occurs during switching, i.e. 0.4 VA max. @ 20 V AC or DC max.

Recommended Contact Materials vs Voltage and Current



Notes:

+ To maximum switch rating.

** For high reliability at these low levels, extra gold plating recommended, consult Customer Service Center.

Tact Switches

The choice of contact material to be used depends on what is expected of the switch in terms of electrical properties and under consideration of the ambient condition.

Two different contact materials have proved themselves to be especially suitable:

Contact Material	Characteristics
Gold (3)	a) For switching levels < 12 V and < 100 mA b) For application in corrosive atmospheres. c) For applications at V and A levels including infrequent usage. In this case, please contact us directly in order to select the most suitable switch for your application.
Silver (1)	For switching levels > 0.5 V and > 100 mA under normal ambient conditions.

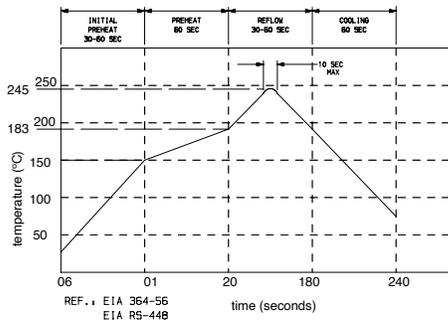
Soldering and Cleaning

Most manufacturing and field problems experienced by users of unsealed switches are caused by contamination of the internal switch contacts during soldering and cleaning processes. Switches may become intermittent, especially in low power applications, and may become open during factory testing or later in the field. Care during soldering and cleaning can prevent most process contamination problems encountered.

Please refer to complete product specifications for applicable reflow profile recommended for your selected reference. Product specifications are available through C&K technical contact. The below soldering profiles are for reference only.

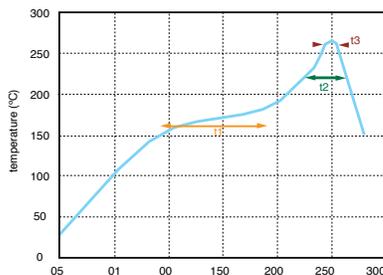
Contamination can occur in both hand soldering and machine soldering processes. Hand soldering and cleaning are acceptable with properly trained personnel, small diameter solder (.030-.040 in.) and low wattage soldering irons (25-40 watts max.). Solder time is approximately 3 seconds maximum. Do not immerse or spray the unsealed areas of the switches with cleaners during flux removal.

Typical SMT Reflow Profile



Pre-heat to a maximum of 200 0 C for 30 seconds.
 Reflow at a maximum of 245 0 C for 10 seconds.
 Maximum time above 183 0 C for 60 seconds.

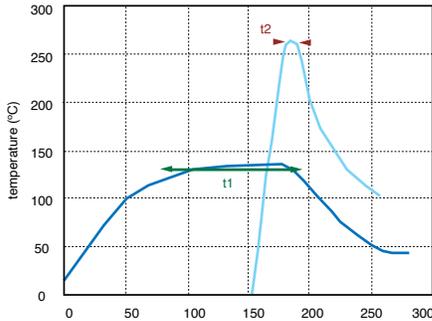
SMT Reflow Soldering Profile of Reference Thermal Shock Resistance



Thermal profile done 2 times on each part tested
 Thermal profile in accordance with CEI 60068-2-58/
 EN 60068-2-58

Contact Material	Characteristics	Lead Free Specification
Time between 150°C and 180°C	t1	90 seconds
Time above 220 0 C	t2	40 seconds
Time at/above 250 0 (peak)	t3	10 seconds
Peak temperature	T peak	260°C 0/+5°C

Wave Soldering Profile of Reference Thermal Shock Resistance



Note:
Not all of C&K Components products have been tested to this profile.
Please refer to product section for more information.

Thermal profile done in 2 times:

- Preheat thermal profile ———
- Soldering heat resistance ———
- Thermal profile done 2 times on each part listed
- Thermal profile in accordance with CEI 60068-2-58/
EN 60068-2-58

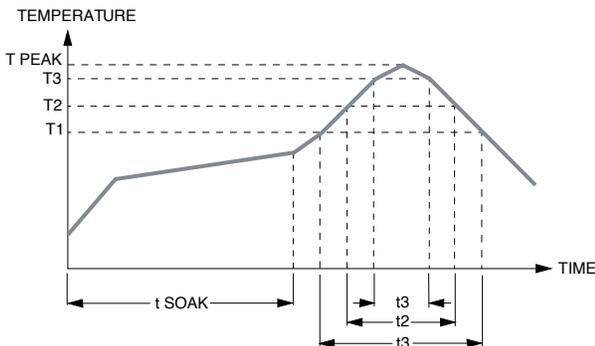
Parameter	Reference	Lead Free Specification
Preheat time exposure	t1	Between 100s and 120s
Preheat	T1	>120° C
Time at max. body temp	t2	10 seconds max
Peak board bottom temp	T2	260°C 0/+5°C

RoHS Definitions and Specifications

RoHS compliant = Complies with EU directive 2002/95/EC restriction of hazardous substances.
RoHS compatible = Compatible with lead free soldering process.

Reflow Solder Profile Requirement

Parameter	Reference	Tin/Lead Specification	Lead Free Specification
Preheat Temperature Gradient		+1-4 C/sec	+1-4 C/sec
Soak Time	t Soak	2 min. max	2-3 min.
Time Above 100C		Not Specified	420 sec. max
Time Above 183C		60-120 sec.	120-180 sec.
Time Above 217C	t1 / T1	Not Specified	90 sec. max
Time Above 230C	t2 / T2	10-40 sec.	20-60 sec.
Time Above 250C	t3 / T3	0	10 sec. max
Peak Temperature	T Peak	235 -0/+5C	255 -0/+5C
Cooling Temperature Gradient		-6C/sec. max	-6C/sec. max

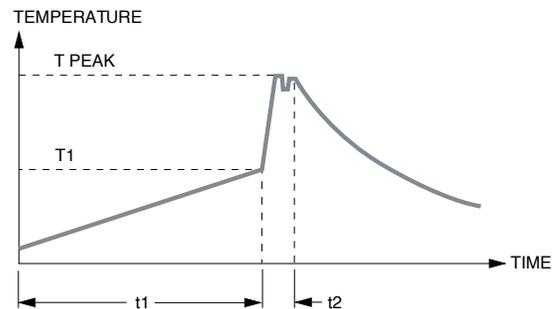


TIN/LEAD SPECIFICATIONS ARE TAKEN FROM:
ANSI/IPC-9504 JUNE 1998

Wave Solder Requirement For Soldering Heat Resistance Testing

Parameter	Reference	Tin/Lead Specification	Lead Free Specification
Preheat Temperature Gradient		+1-4 C/sec.	+1-4 C/sec.
Soak Time	t1	2 min. max	2-3 min.
Preheat Temp	T1	> 90° C	> 100° C
Solder Pot Temp	T2	245° - 260° C	260° - 275° C
Solder Pot Contact Time	t2	2 - 2.5 sec.	2 - 3.5 sec.
Lead Thermal Trans. Spike		> 130° C	> 130° C
Component Body Temp		> 180° C	> 200° C
Time @ Max. Body Temp		> 10 sec.	> 10 sec.
Peak Temperature	T Peak	235° -0°/+5°C	255° -0°/+5°C
Cooling Temperature Gradient		-6C/sec. max	-6C/sec. max

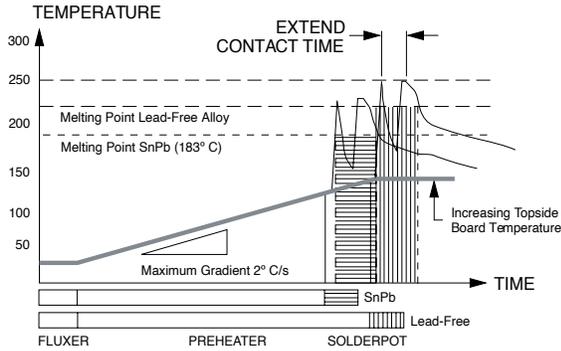
Wave Solder Thermal Profile (TH Components)



TIN/LEAD SPECIFICATIONS ARE TAKEN FROM:
ANSI/IPC-9504 SURFACE MOUNT TECHNOLOGY ASSOCIATION
COOKSON ELECTRONICSC COOKSON ELECTRONICS
National Electronics National Electronics
Manufacturing Initiative, Inc. M manufacturing Initiative, Inc.

Wave Solder Requirement For Soldering Heat Resistance Testing

Difference between SnPb and Lead-free Wave Soldering

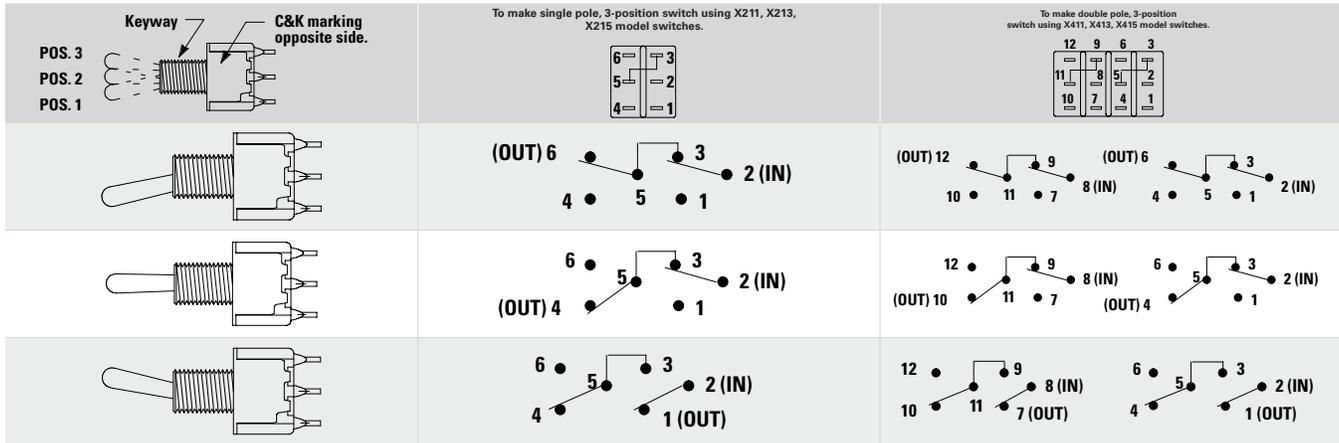


Notes:
Not all of C&K Components products have been tested to these profiles. Please refer to product section for more information.

Wiring for 3-Way Switches

3-Position toggle and rocker switches with ON-ON-ON switch functions may be externally wired for '3-way' function. See wiring diagram and schematics below.

Note:
Jumpers are added by customer.



These switch series have one or more models that may be wired to achieve SP3T or DP3T functions:
7000 Series (including UL/CSA Models), E Series, ET Series, T Series.

Mode of Switching

We can deliver some switch types with non-shorting (BBM=Break-Before-Make) or shorting (bridging): MBB=Make-Before-Break) modes of switching. In the non-shorting (BBM) mode there is no connection between two neighboring contacts during the switching operation. The moving contact leaves its starting position before making contact in the next position. In the shorting (MBB) mode a bridging is effected during the switching operation.

The mode of switching is non-shorting unless otherwise specified.

- U=Changeover contact
- A=Make contact (SPST N.O.)
- R=Break contact (SPST N.C.)